# SEMTECH APPROVED PRODUCTS

# E2801/E2801LF GR-253-Core SMC (SONET minimum clock) and ITU G.813 Option 2 Minature Surface Mount TCXO

ISSUE 2 ; 13 JUNE 2005

#### Nominal Frequency, Fo

■ 20.0MHz

#### Supply Voltage

■ 3.3V ±5%

#### **Input Current**

 $\blacksquare \le 6mA$ 

#### Output

Type : HCMOS
 Load : 15pF max
 Vol : ≤ 0.1 Vs
 Voh : ≥ 0.9 Vs

■ Duty Cycle @ 50%: 45% to 55%
■ RiseTime, 10% to 90%: ≤8ns

■ FallTime, 90% to 10%:<8ns

# $\textbf{Holdover Stability} \ \leq \pm 4.6 ppm$

Incl.

■ Temperature, -40 to 85°C:

■ Supply Voltage, 3.3V ± 5%

■ Ageing 24 hours: ≤ ±0.5ppm, equivalent to ≤±5.8x10<sup>-12</sup>/sec

# Free-Run Accuracy $\leq \pm 20.0$ ppm ref.Fo Incl.

■ Calibration @ 25°C,

■ Temperature -40 to 85°C

■ Supply Voltage 3.3V ±5%,

■ Load 15pF ±10%

■ Reflow Soldering and Ageing 20 years

#### **Phase Noise**

10Hz ≤ -85dBc/Hz
 100Hz ≤-110dBc/Hz
 1kHz ≤-125dBc/Hz
 ≥10kHz ≤-135dBc/Hz

#### Tri-state

■ Pad 8 open circuit or ≥0.6Vs : Output Enabled

■ Pad 8 ≤ 0.2Vs : Output in tri-state mode

When in tri-state, the output stage is disabled but the oscillator and compensation circuit are still active, (Current consumption ≤ 1mA)

#### Marking (laser)

- Manufacturers ID (CMAC)
- Manufacturers identifier (xx)
- Pad 1 / Static Sensitivity Identifier (Δ)
- Abbreviated Part Number (2801)
- Oscillator's Date of Manufacture (YW)

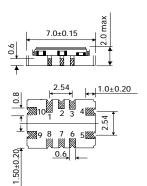


Note: Production parts will be marked in this format. Sample marking may vary.

#### **Environmental Specification**

- Storage Temperature Range: -55 to 125°C
- Vibration: IEC 60068-2-6 Test Fc Procedure B4, 10-60Hz 1.5mm displacement, at 98.1 m/s², 30 minutes in each of three mutually perpendicular axes at 1 octave per minute.
- Shock: IEC 60068-2-27 Test Ea, 980m/s<sup>2</sup> acceleration for 6ms duration, 3 shocks in each direction along three mutually perpendicular axes.
- Solderability: MIL-STD-202, Method 208, Catergory 3.
   Resistance to Soldering heat: 260°C / 10 seconds exposure
- RoHS/Soldering: Parts with the suffix 'LF' on the part number are fully compliant with the European Union directive 2002/95/EC on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Note: The RoHS compiant parts are suitable for assembly using both Lead-free solders (see Lead-free Reflow soldering profile) and Tin/Lead solders (see Tin/Lead Reflow soldering profile).

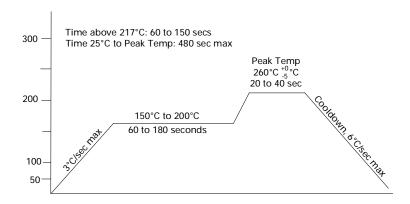


1.Do not connect
2.N/C
3.Do not connect
4.GND
5.Output
6.N/C
7.N/C
8.Tri-state Control\*
9.Supply, +Vs
10.Do not connect, or connect to GND
\*Leave unconnected if not required

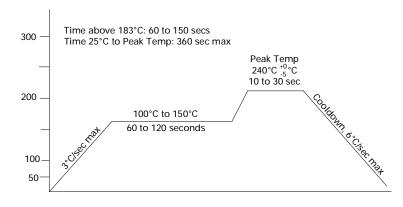
Pad Connections



## Lead Free Reflow Soldering Profile \*



### Tin / Lead Reflow Soldering Profile \*



## \*Note:

These profiles were used during the qualification testing of the product and therefore represent worst case conditions. They are not recommended for use by the customer in the actual assembly of these parts